

## \*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

1.75

3.35

**DATE 31 OCT 2006** 

## NOTES:

- DIMENSIONING AND TOLERANCING PER
- 2. CONTROLLING DIMENSION: MILLIMETER.
  3. DIMENSION & APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM TERMINAL.
  4. COPLANARITY APPLIES TO THE EXPOSED
- PAD AS WELL AS THE TERMINALS.

	MILLIMETERS	
DIM	MIN	MAX
Α	0.70	0.80
A1	0.00	0.05
A3	0.20 REF	
b	0.20	0.30
D	4.00 BSC	
D2	3.20	3.40
Е	3.00 BSC	
E2	1.60	1.80
е	0.50 BSC	
K	0.20	
L	0.30	0.50

## **GENERIC MARKING DIAGRAM\***



= Specific Device Code XXXXX = Assembly Location Α = Year

= Work Week WW = Pb-Free Package

(Note: Microdot may be in either location)

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

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STATUS:	ON SEMICONDUCTOR STANDARD	accessed directly from the Document versions are uncontrolled except	
NEW STANDARD:		"CONTROLLED COPY" in red.	
DESCRIPTION:	WDFN12, 3X4X0.75, 0.5 P		PAGE 1 OF 2

12 X

0.55

0.50 PITCH

DIMENSIONS: MILLIMETERS

0.30



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